

CLAIM AMENDMENTS

1. (Currently Amended) A chemical processor comprising:
a chemical processing cup, in which a member-to-be-processed is to be ~~provided~~
placed; and
a pumping device for circulating a liquid chemical within said chemical processing
cup, wherein ~~said the~~ member-to-be-processed has a surface-to-be-processed which is
placed face up in said chemical processing cup, said surface-to-be-processed is chemically
processed while ~~said the~~ liquid chemical is circulated along ~~said the~~ surface-to-be-processed
in substantially a ~~given~~ single direction at all times and at a velocity gradient of at least
300/second ~~or more~~.

2. (Currently Amended) The chemical processor according to claim 1, wherein said
chemical processing cup ~~has~~ includes a chemical inlet port and a chemical drain port, and
including a regulation member ~~capable of regulating an~~ effective aperture area ~~is provided~~
located at said chemical drain port.

3. (Currently Amended) The chemical processor according to claim 1, ~~wherein~~
including a flow rate regulation plate opposing ~~said the~~ surface-to-be-processed ~~is provided~~
and located in said chemical processing cup.

4. (Currently Amended) A chemical processing method comprising ~~the steps of~~
placing a member-to-be-processed having a plurality of blind holes ~~formed~~ in a
surface-to-be-processed in a chemical processing cup ~~such that~~ with said surface-to-be-
processed ~~is~~ oriented upward; and
chemically processing said surface-to-be-processed ~~while~~ by circulating a liquid
chemical ~~is circulated~~ along said surface-to-be-processed in substantially a ~~given~~ single
direction at all times and at a velocity gradient of at least 300/second ~~or more~~.

5. (Currently Amended) The method of processing a chemical according to claim 4,
wherein said member-to-be-processed is a semiconductor wafer, and including cleaning the
insides of said blind holes ~~are cleansed~~ with said liquid chemical.

6. (Currently Amended) The method of processing a chemical according to claim 4,
wherein said member-to-be-processed is a semiconductor wafer, and including plating said
blind holes ~~are plated with~~ using said liquid chemical.

7. (Currently Amended) The method of processing a chemical according to claim 4, wherein ~~an~~ aspect ratio of said blind ~~hole~~ holes is no more than 2 ~~or less~~.

8. (Currently Amended) A method for manufacturing a semiconductor device comprising ~~the steps of~~:

placing a semiconductor wafer having a plurality of blind holes ~~formed~~ in a surface-to-be-processed in a chemical processing cup ~~such that~~ with said surface-to-be-processed is oriented upward;

chemically processing said surface-to-be-processed ~~while~~ by circulating a liquid chemical ~~is circulated~~ along said surface-to-be-processed in substantially a ~~given~~ single direction at all times and at a velocity gradient of at least 300/second ~~or more~~.

9. (Currently Amended) The method for manufacturing a semiconductor device according to claim 8, ~~wherein~~ including cleaning the insides of said blind holes ~~is cleansed~~ while said semiconductor wafer is chemically processed.

10. (Currently Amended) The method for manufacturing a semiconductor device according to claim 8, ~~wherein~~ including plating said blind holes ~~are plated~~ while said semiconductor wafer is chemically processed.

11. (Currently Amended) The method of manufacturing a semiconductor device according to claim 8, wherein ~~an~~ aspect ratio of said blind ~~hole~~ holes is no more than 2 ~~or less~~.